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APPLICATION N	O.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/091,544		03/07/2002	Kazutaka Shibata	ROH-049	9071
23353	7590	01/03/2003			
1012211		N & GRAUER PLL	EXAMINER		
LION BUILDING 1233 20TH STREET N.W., SUITE 501				THAI, LUAN C	
WASHINGTON, DC 20036				ART UNIT	PAPER NUMBER
				2827	2827
				DATE MAILED: 01/02/2002	

Please find below and/or attached an Office communication concerning this application or proceeding.

w it		Application No.	Applicant(s)				
	Office Action Summers	10/091,544	SHIBATA, KAZUTAKA				
	Office Action Summary	Examiner	Art Unit				
		Luan Thai	2827				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply							
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). Status							
1)	Responsive to communication(s) filed on						
2a)□		— · is action is non-final.					
3)	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213. Disposition of Claims							
4)⊠ Claim(s) <u>1-7</u> is/are pending in the application.							
4a) Of the above claim(s) is/are withdrawn from consideration.							
5)	Claim(s) is/are allowed.						
6)🖂	6)⊠ Claim(s) <u>1-7</u> is/are rejected.						
7)	Claim(s) is/are objected to.						
8)□	Claim(s) are subject to restriction and/or	r election requirement.					
Application Papers							
9)☐ The specification is objected to by the Examiner.							
10) 🔲 🗆	The drawing(s) filed on is/are: a)□ accep	oted or b) objected to by the Exa	miner.				
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
11)[The proposed drawing correction filed on		oved by the Examiner.				
If approved, corrected drawings are required in reply to this Office action.							
12) The oath or declaration is objected to by the Examiner.							
Priority under 35 U.S.C. §§ 119 and 120							
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).							
a)⊠ All b)□ Some * c)□ None of:							
	1. Certified copies of the priority documents have been received.						
	2. Certified copies of the priority documents have been received in Application No						
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 							
14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).							
a) ☐ The translation of the foreign language provisional application has been received. 15)☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.							
Attachment(s)							
1) Notice 2) Notice	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449) Paper No(s) _	5) Notice of Informal	y (PTO-413) Paper No(s) Patent Application (PTO-152)				

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DETAILED ACTION

Priority

1. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Oath/Declaration

2. The declaration filed 03/07/02 is acceptable.

Claim Rejections - 35 USC § 102

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in-
- (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effect under this subsection of a national application published under section 122(b) only if the international application designating the United States was published under Article 21(2)(a) of such treaty in the English language; or
- (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that a patent shall not be deemed filed in the United States for the purposes of this subsection based on the filing of an international application filed under the treaty defined in section 351(a).
- 4. Claims 1-5 and 7 are rejected under 35 U.S.C. 102(e) as being anticipated by Morrell et al (5,895,976).

The figures and reference numbers referred to in this office action are used merely to indicate an example of a specific teaching and are not to be taken as limiting.

Regarding claims 1-5 and 7, Morrell et al (see specifically figures 3-4) a semiconductor device comprising: a polymeric substrate 14 (Col. 5, lines 19+); a semiconductor chip 12 having one surface bonded to a surface of the substrate 14 via fillets 38; a warp preventing sheet 18 (e.g., a polymeric reinforcement

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layer 18) bonded to the other surface of the semiconductor chip 12, wherein the semiconductor device is a thin semiconductor device of a chip-size package type. Morrell et al further disclose the base material of the substrate 14 and the warp preventing sheet 18 being made of the same material (e.g., polymer) and having the same coefficient of elasticity and the coefficient of thermal expansion (Col. 5, lines 19+, and lines 31+).

5. Claims 1-6, are rejected under 35 U.S.C. 102(e) as being anticipated by Senba et al (6,188,127).

The figures and reference numbers referred to in this office action are used merely to indicate an example of a specific teaching and are not to be taken as limiting.

Regarding claims 1-6, Senba et al. disclose (see specifically figure 4E) a semiconductor device comprising: a first polyimide substrate 2 (e.g., a polyimide carrier film 2, Col. 5, lines 34+); a semiconductor chip 1' having one surface bonded to a surface of the substrate 2 via bumps 4 and resin 8; a second polyimide substrate 2' (e.g., another polyimide carrier film) bonded to the other surface of the semiconductor chip 1'. Since the first polyimide substrate 2 (from which chip 1' is mounted on) and the second polyimide substrate 2' (bonded on the top surface of the chip) are made of the same material and have the same thickness, both the substrates 2 and 2' inherently have the same coefficient of elasticity and the same coefficient of thermal expansion. Also, Senba et al.'s semiconductor device that comprises the first polyimide substrate 2, semiconductor chip 1, and the second polyimide substrate 2', are similar as that

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of the claimed device structure; thus, the polyimide substrate 2', which is bonded

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on the top (non-active surface) of the semiconductor chip 1', would inherently

have a characteristic of warp preventing for the device.

6. Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Luan Thai whose telephone number is (703) 308-1211.

The examiner can normally be reached on 7:00 AM - 4:00 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, David L. Talbott can be reached on (703) 305-9883. The fax phone

numbers for the organization where this application or proceeding is assigned are (703)

308-7722 for regular communications and (703) 308-7724 for After Final

communications.

Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the receptionist whose telephone number is (703) 308-

0956.

Luan Thai

December 29, 2002

Fig. 4A

FACE-DOWN BONDING

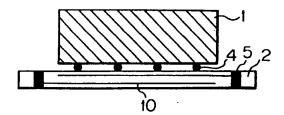


Fig. 4B

SEALING WITH RESIN

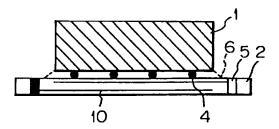


Fig. 4C

GRINDING OR THE LIKE

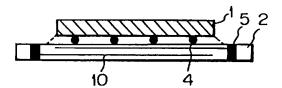


Fig. 4D

FORMING BUMPS

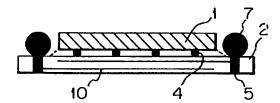


Fig. 4E

STACKING

